

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0904NSI	**Issued**	24. February 2022
MA#	MA005699997		
Package	PG-TDSON-8-6	**Weight***	118.03 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.24	0.24	2411	2411
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
	non noble metal	copper	7440-50-8	37.762	31.99	32.03	319946	320362
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	394	394
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		748	
	plastics	epoxy resin	-	6.268	5.31		53105	
	inorganic material	silicondioxide	60676-86-0	37.783	32.02	37.40	320131	373984
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12299	12299
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1402	1402
solder	non noble metal	tin	7440-31-5	0.009	0.01		80	
	noble metal	silver	7440-22-4	0.012	0.01		100	
	non noble metal	lead	7439-92-1	0.450	0.38	0.40	3813	3993
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.89	18.92	188872	189118
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.59	9.60	95912	96037
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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